

Features

- Low RDS(ON)
- Low Dense Cell Design
- Reliable and Rugged

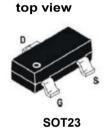
Application

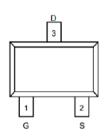
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

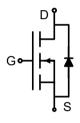
Product Summary



V _{DSS}	100	V
R _{DS(ON)-Typ.}	180	mΩ
I _D	2	Α







Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vos	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	2	Α
Drain Current-Pulsed (Note 1)	I _{DM}	5	Α
Maximum Power Dissipation	P _D	1.1	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient Note 2	$R_{ heta JA}$	120	°C/W

Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100	110	-	٧
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	ı	1	μΑ



Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.8	2.5	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =1A	-	180	250	mΩ	
Forward Transconductance	g FS	V _{DS} =5V,I _D =1A	1	-	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C _{lss}	V _{DS} =50V,V _{GS} =0V,	-	190	-	PF	
Output Capacitance	Coss	F=1.0MHz	-	22	-	PF	
Reverse Transfer Capacitance	C _{rss}	1 - 1.0IVII 12	-	13	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		ı	6	-	nS	
Turn-on Rise Time	t _r	V_{DD} =50V, I_{D} =1.3A, R_{L} =39 Ω	-	10	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =1 Ω	-	10	-	nS	
Turn-Off Fall Time	t _f		-	6	-	nS	
Total Gate Charge	Qg	V _{DS} =50V,I _D =1.3A,	-	5.2		nC	
Gate-Source Charge	Q_{gs}	$V_{DS}=30V,I_{D}=1.3A,$ $V_{GS}=10V$	-	0.75	-	nC	
Gate-Drain Charge	Q _{gd}	VGS-10V	-	1.4	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1.3A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	2	Α	

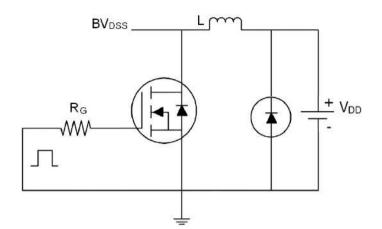
Notes:

- 1. Repetitive Ratin: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- 4. Guaranteed by desi n, not subject to production

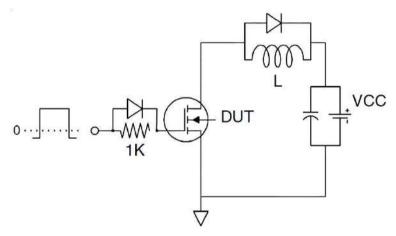


Test Circuit

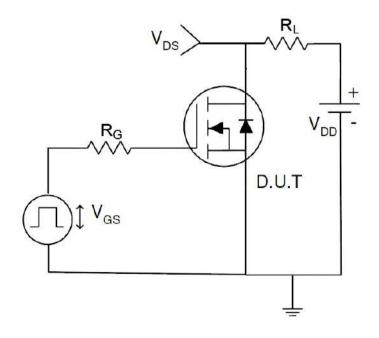
1) E_{AS} test circuit



2) Gate charge test circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

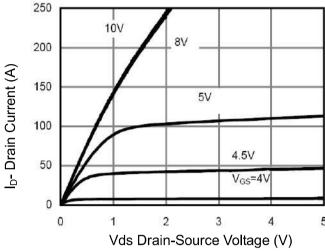


Figure 1 Output Characteristics

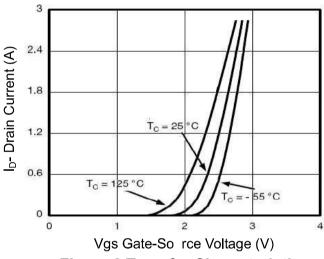


Figure 2 Transfer Characteristics

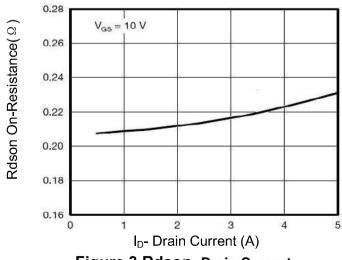


Figure 3 Rdson- Drain Current

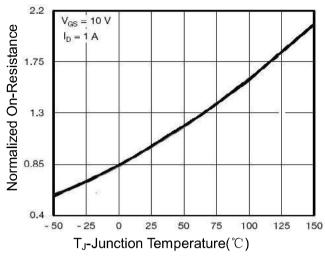


Figure 4 Rdson-JunctionTemperature

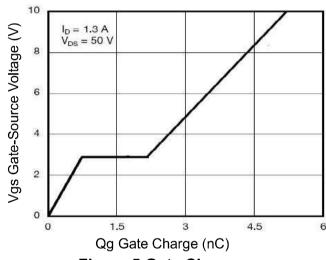


Figure 5 Gate Charge

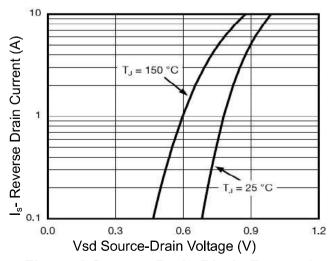


Figure 6 Source- Drain Diode Forward



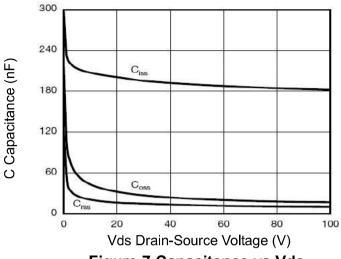


Figure 7 Capacitance vs Vds

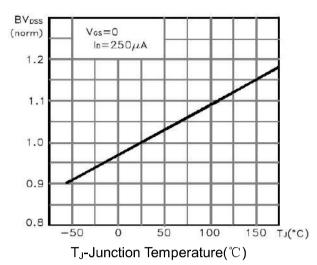


Figure 9 BV_{DSS} vs Junction Temperature

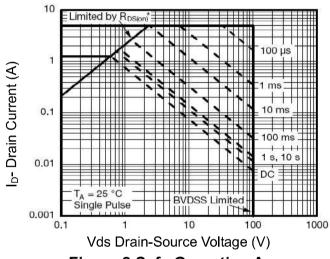


Figure 8 Safe Operation Area

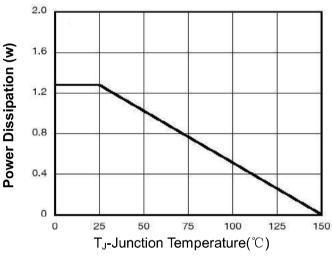
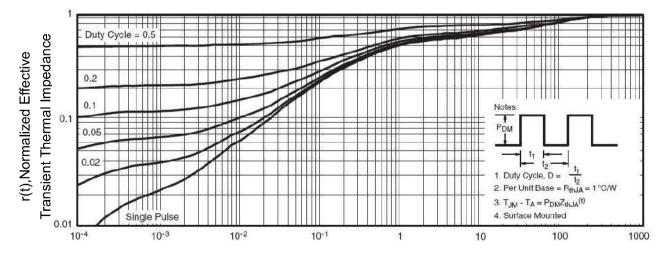


Figure 10 Power De-rating



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



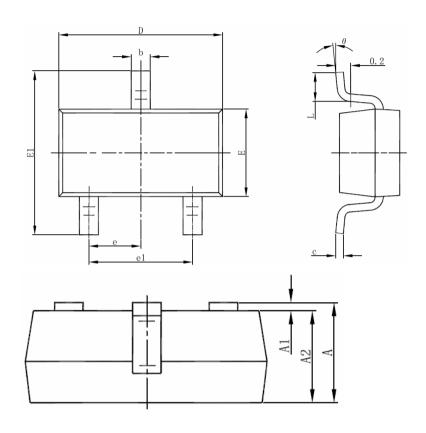
Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
JME100N02ZA-R	100N02	SOT23	Tape&Reel	3000

PACKAGE	MARKING
SOT23	1002 Date Code



SOT-23 PACKAGE INFORMATION



C. mh a l	Dimensions In Millimeters		Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°



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